

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUC45N04S6L063H	**Issued**	15. May 2021
MA#	MA004441484		
Package	PG-TDSON-8-57	**Weight***	99.14 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.195	0.20	0.20	1972	1972
chip_2	inorganic material	silicon	7440-21-3	0.195	0.20	0.20	1972	1972
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		137	
	non noble metal	iron	7439-89-6	0.045	0.05		457	
	non noble metal	copper	7440-50-8	45.219	45.61	45.67	456111	456705
wire	noble metal	gold	7440-57-5	0.061	0.06	0.06	615	615
encapsulation	organic material	carbon black	1333-86-4	0.082	0.08		825	
	plastics	epoxy resin	-	6.458	6.51		65136	
	inorganic material	silicondioxide	60676-86-0	34.331	34.63	41.22	346294	412255
leadfinish	non noble metal	tin	7440-31-5	0.512	0.52	0.52	5167	5167
plating	noble metal	silver	7440-22-4	0.240	0.24	0.24	2419	2419
solder	non noble metal	tin	7440-31-5	0.013	0.01		133	
	noble metal	silver	7440-22-4	0.016	0.02		166	
	non noble metal	lead	7439-92-1	0.628	0.63	0.66	6338	6637
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			33	
	non noble metal	iron	7439-89-6	0.011	0.01		109	
	non noble metal	copper	7440-50-8	10.832	10.93	10.94	109258	109400
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.283	0.29	0.29	2854	2858
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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